

SOT635-1

plastic thermal enhanced ball grid array package; 596 balls;
body 40 x 40 x 1.75 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA596
Package type industry code	HBGA596
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	14-1-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	39.8	-	40	40.2	mm
E	package width	39.8	-	40	40.2	mm
A	seated height	[tbd]	-	2.54	2.54	mm
A ₂	package height	1.55	-	1.75	1.91	mm
n ₂	actual quantity of termination	-	-	596	-	



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2. Package outline

HBGA596: plastic thermal enhanced ball grid array package; 596 balls;
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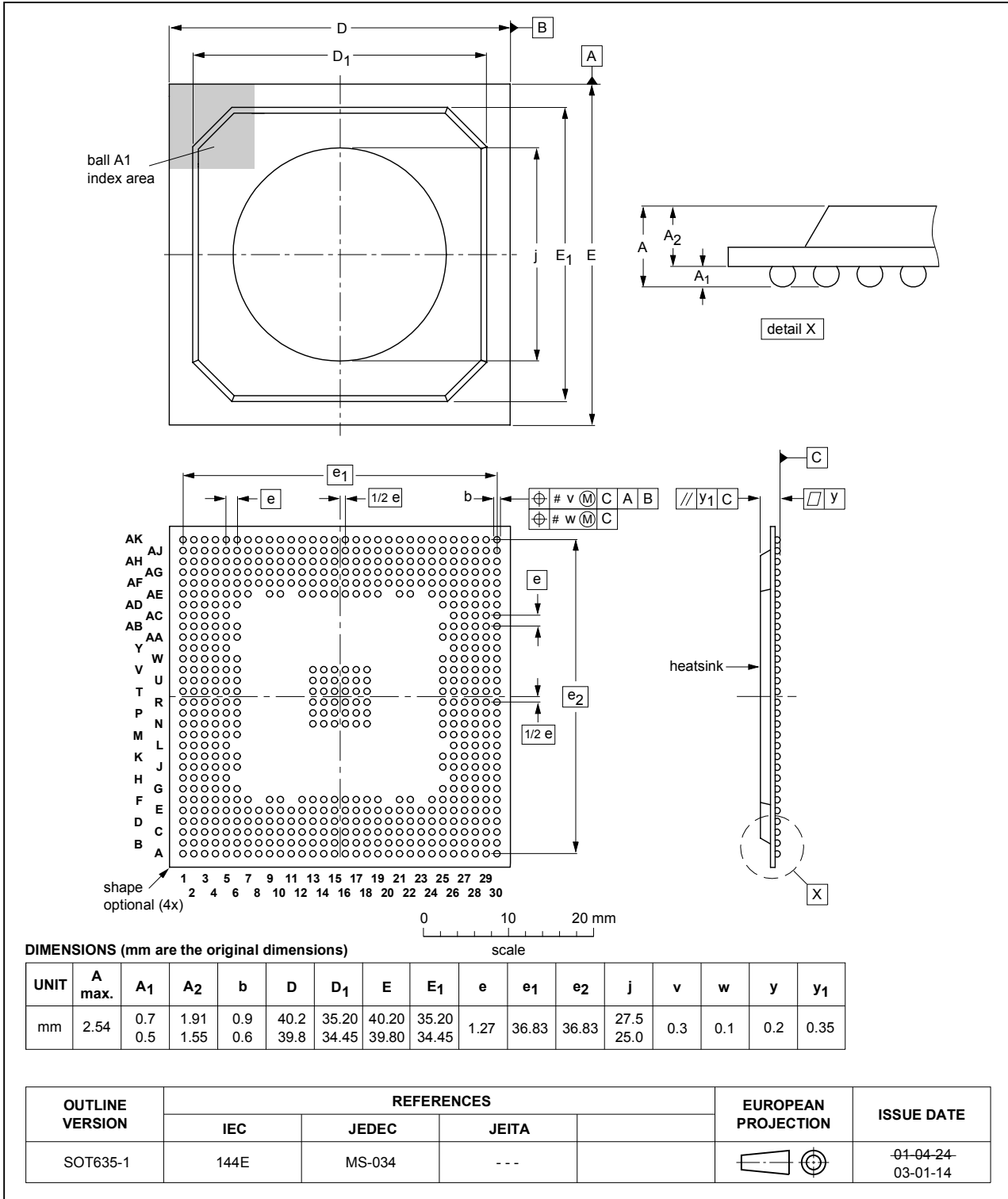


Fig. 1. Package outline HBGA596 (SOT635-1)

3. Soldering

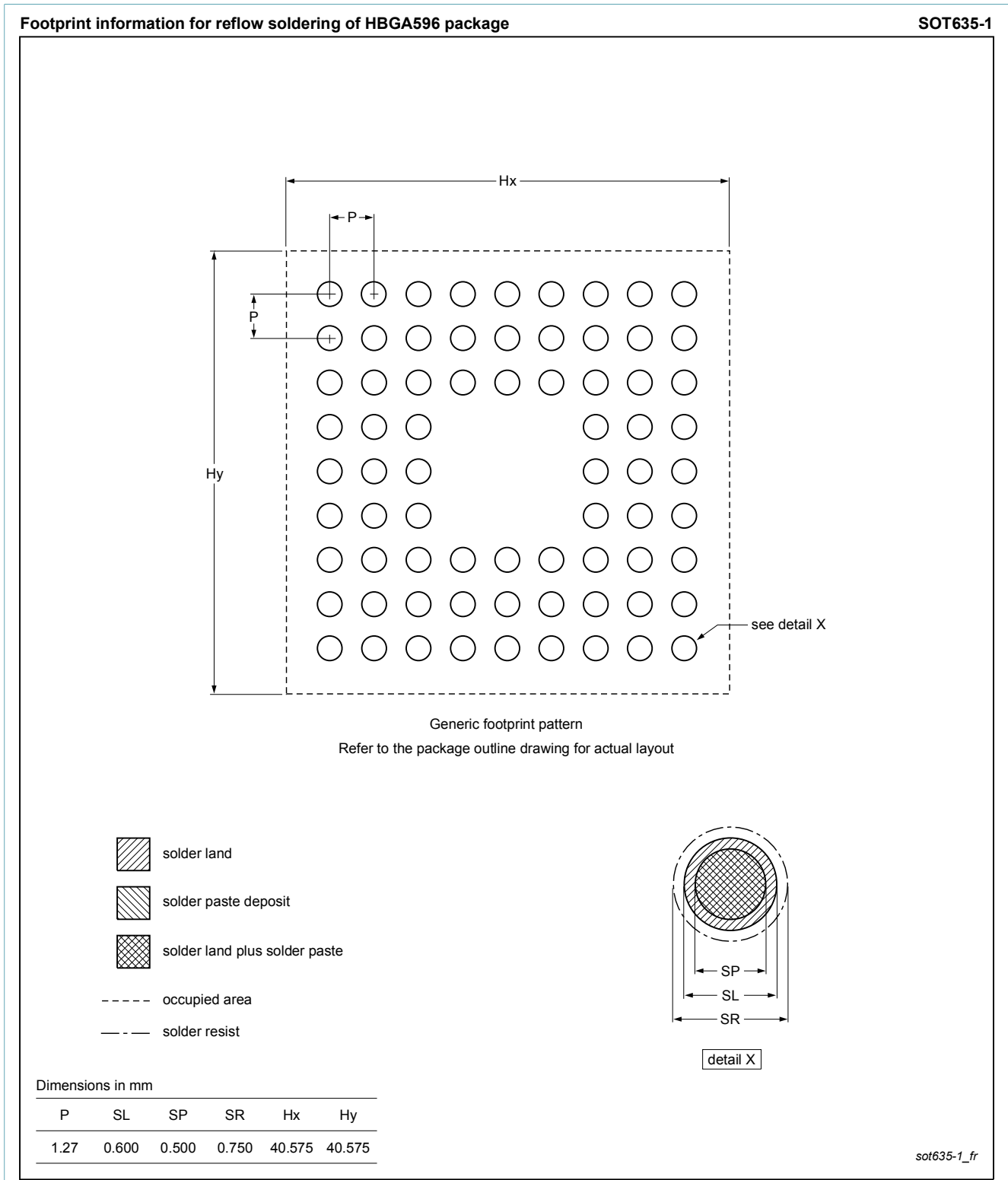


Fig. 2. Reflow soldering footprint for HBGA596 (SOT635-1)

4. Legal information

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Date of release: 8 February 2016
